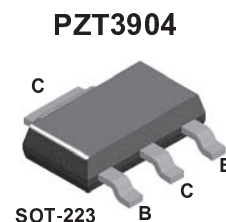
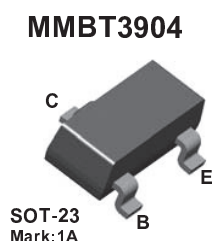


2N3904 / MMBT3904 / PZT3904 NPN General Purpose Amplifier

Features

- This device is designed as a general purpose amplifier and switch.
- The useful dynamic range extends to 100 mA as a switch and to 100 MHz as an amplifier.



Absolute Maximum Ratings* $T_a = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{CEO}	Collector-Emitter Voltage	40	V
V_{CBO}	Collector-Base Voltage	60	V
V_{EBO}	Emitter-Base Voltage	6.0	V
I_C	Collector Current - Continuous	200	mA
T_J, T_{stg}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics $T_a = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Max.			Units
		2N3904	*MMBT3904	**PZT3904	
P_D	Total Device Dissipation Derate above 25°C	625	350	1,000	mW
		5.0	2.8	8.0	mW/ $^\circ\text{C}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	83.3			$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	357	125	$^\circ\text{C}/\text{W}$

* Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06".

** Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm; mounting pad for the collector lead min. 6 cm².

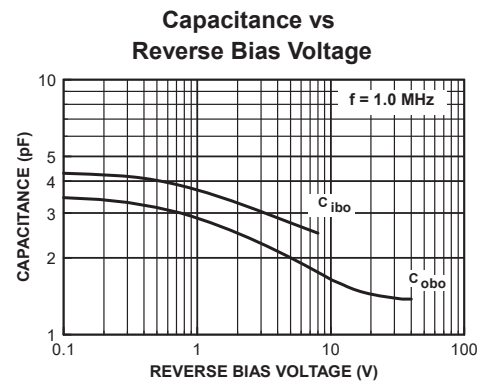
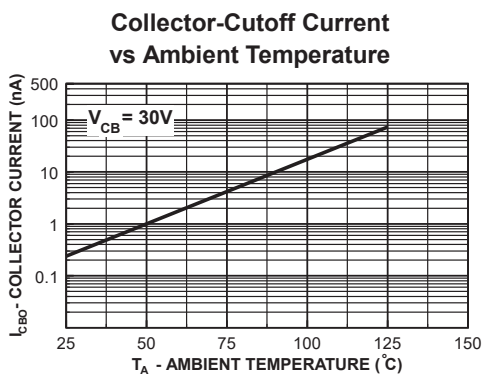
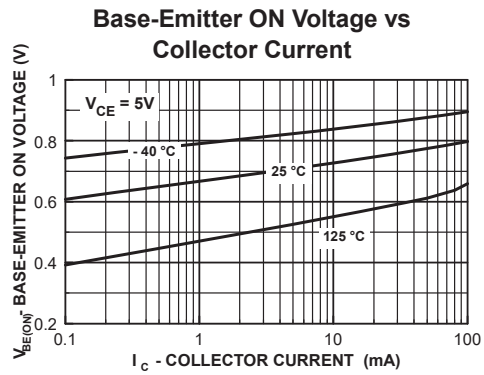
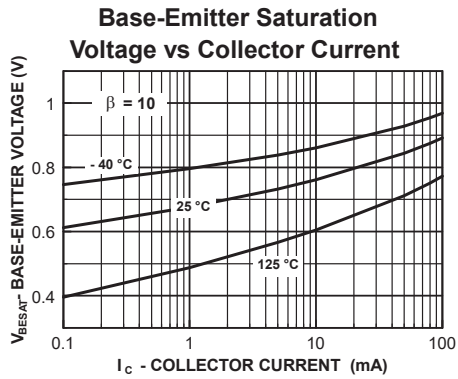
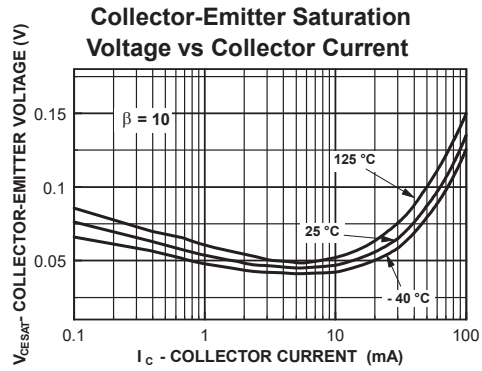
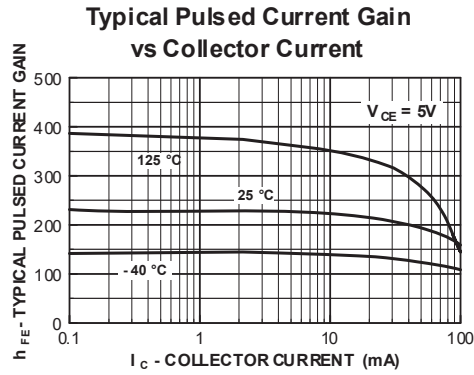
Electrical Characteristics $T_a = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
OFF CHARACTERISTICS					
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage	$I_C = 1.0\text{mA}, I_B = 0$	40		V
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage	$I_C = 10\mu\text{A}, I_E = 0$	60		V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage	$I_E = 10\mu\text{A}, I_C = 0$	6.0		V
I_{BL}	Base Cutoff Current	$V_{CE} = 30\text{V}, V_{EB} = 3\text{V}$		50	nA
I_{CEX}	Collector Cutoff Current	$V_{CE} = 30\text{V}, V_{EB} = 3\text{V}$		50	nA
ON CHARACTERISTICS*					
h_{FE}	DC Current Gain	$I_C = 0.1\text{mA}, V_{CE} = 1.0\text{V}$ $I_C = 1.0\text{mA}, V_{CE} = 1.0\text{V}$ $I_C = 10\text{mA}, V_{CE} = 1.0\text{V}$ $I_C = 50\text{mA}, V_{CE} = 1.0\text{V}$ $I_C = 100\text{mA}, V_{CE} = 1.0\text{V}$	40 70 100 60 30	300	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 10\text{mA}, I_B = 1.0\text{mA}$ $I_C = 50\text{mA}, I_B = 5.0\text{mA}$		0.2 0.3	V V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C = 10\text{mA}, I_B = 1.0\text{mA}$ $I_C = 50\text{mA}, I_B = 5.0\text{mA}$	0.65	0.85 0.95	V V
SMALL SIGNAL CHARACTERISTICS					
f_T	Current Gain - Bandwidth Product	$I_C = 10\text{mA}, V_{CE} = 20\text{V},$ $f = 100\text{MHz}$	300		MHz
C_{obo}	Output Capacitance	$V_{CB} = 5.0\text{V}, I_E = 0,$ $f = 1.0\text{MHz}$		4.0	pF
C_{ibo}	Input Capacitance	$V_{EB} = 0.5\text{V}, I_C = 0,$ $f = 1.0\text{MHz}$		8.0	pF
NF	Noise Figure	$I_C = 100\mu\text{A}, V_{CE} = 5.0\text{V},$ $R_S = 1.0\text{k}\Omega,$ $f = 10\text{Hz to } 15.7\text{kHz}$		5.0	dB
SWITCHING CHARACTERISTICS					
t_d	Delay Time	$V_{CC} = 3.0\text{V}, V_{BE} = 0.5\text{V}$		35	ns
t_r	Rise Time	$I_C = 10\text{mA}, I_{B1} = 1.0\text{mA}$		35	ns
t_s	Storage Time	$V_{CC} = 3.0\text{V}, I_C = 10\text{mA},$		200	ns
t_f	Fall Time	$I_{B1} = I_{B2} = 1.0\text{mA}$		50	ns

* Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2.0\%$ **Ordering Information**

Part Number	Marking	Package	Packing Method	Pack Qty
2N3904BU	2N3904	TO-92	BULK	10000
2N3904TA	2N3904	TO-92	AMMO	2000
2N3904TAR	2N3904	TO-92	AMMO	2000
2N3904TF	2N3904	TO-92	TAPE REEL	2000
2N3904TFR	2N3904	TO-92	TAPE REEL	2000
MMBT3904	1A	SOT-23	TAPE REEL	3000
MMBT3904_D87Z	1A	SOT-23	TAPE REEL	10000
PZT3904	3904	SOT-223	TAPE REEL	2500

Typical Performance Characteristics



Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Type	Min	Typ	Max	Units
OFF CHARACTERISTICS							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 10\ \mu\text{A}$	All	60			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}$	2N7000			1	μA
						1	mA
		$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$	2N7002 NDS7002A			1	μA
						0.5	mA
I_{GSSF}	Gate - Body Leakage, Forward	$V_{GS} = 15\text{ V}, V_{DS} = 0\text{ V}$	2N7000			10	nA
		$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$	2N7002 NDS7002A			100	nA
I_{GSSR}	Gate - Body Leakage, Reverse	$V_{GS} = -15\text{ V}, V_{DS} = 0\text{ V}$	2N7000			-10	nA
		$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$	2N7002 NDS7002A			-100	nA
ON CHARACTERISTICS (Note 1)							
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 1\text{ mA}$	2N7000	0.8	2.1	3	V
		$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	2N7002 NDS7002A	1	2.1	2.5	
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 500\text{ mA}$	2N7000		1.2	5	Ω
					1.9	9	
		$V_{GS} = 4.5\text{ V}, I_D = 75\text{ mA}$			1.8	5.3	
		$V_{GS} = 10\text{ V}, I_D = 500\text{ mA}$	2N7002		1.2	7.5	
					1.7	13.5	
		$V_{GS} = 5.0\text{ V}, I_D = 50\text{ mA}$			1.7	7.5	
					2.4	13.5	
		$V_{GS} = 10\text{ V}, I_D = 500\text{ mA}$	NDS7002A		1.2	2	
			2	3.5			
				1.7	3		
				2.8	5		
$V_{DS(on)}$	Drain-Source On-Voltage	$V_{GS} = 10\text{ V}, I_D = 500\text{ mA}$	2N7000		0.6	2.5	V
		$V_{GS} = 4.5\text{ V}, I_D = 75\text{ mA}$			0.14	0.4	
		$V_{GS} = 10\text{ V}, I_D = 500\text{ mA}$	2N7002		0.6	3.75	
		$V_{GS} = 5.0\text{ V}, I_D = 50\text{ mA}$			0.09	1.5	
		$V_{GS} = 10\text{ V}, I_D = 500\text{ mA}$	NDS7002A		0.6	1	
		$V_{GS} = 5.0\text{ V}, I_D = 50\text{ mA}$			0.09	0.15	

Typical Electrical Characteristics

2N7000 / 2N7002 / NDS7002A

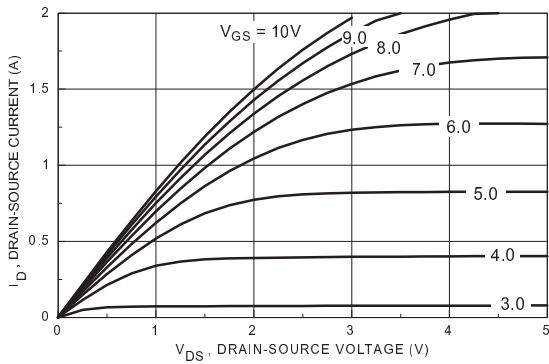


Figure 1. On-Region Characteristics

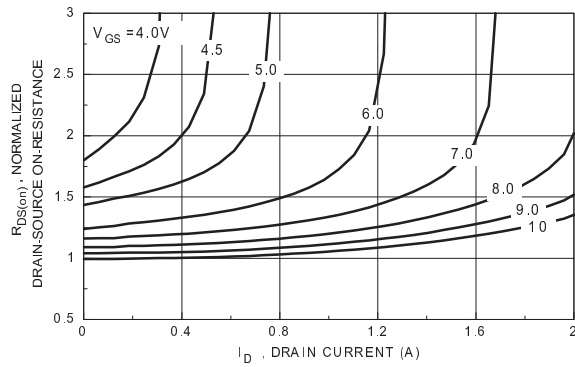


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current

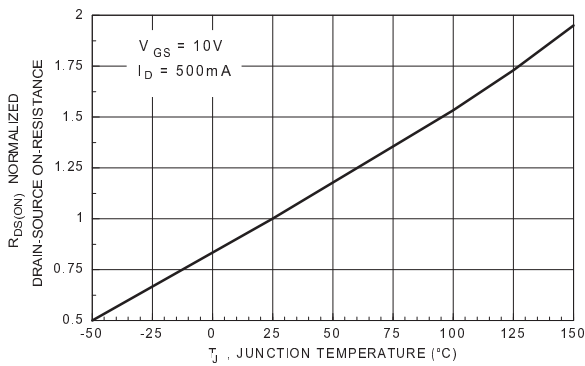


Figure 3. On-Resistance Variation with Temperature

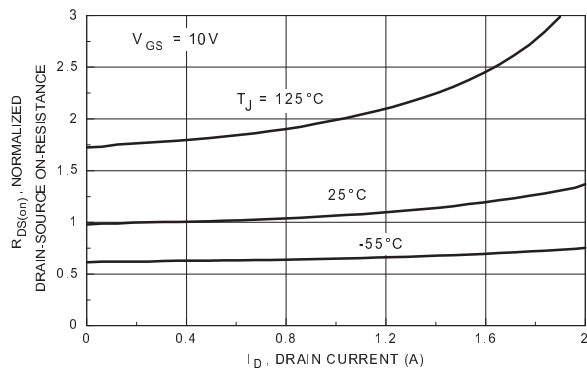


Figure 4. On-Resistance Variation with Drain Current and Temperature

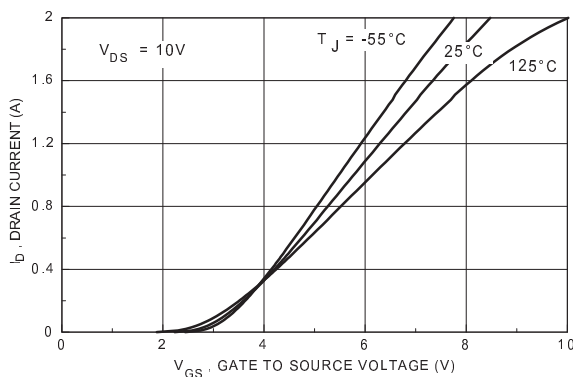


Figure 5. Transfer Characteristics

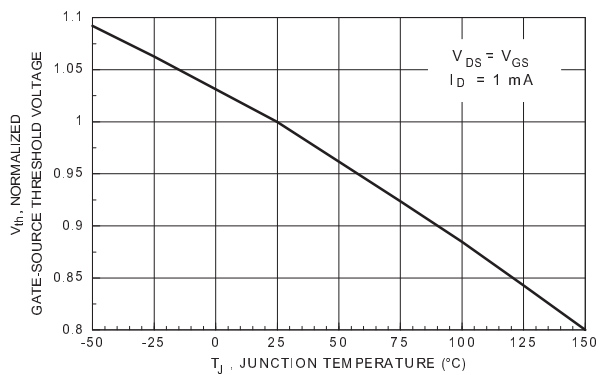


Figure 6. Gate Threshold Variation with Temperature

TIP110, TIP111, TIP112 (NPN); TIP115, TIP116, TIP117 (PNP)

Plastic Medium-Power Complementary Silicon Transistors

Designed for general-purpose amplifier and low-speed switching applications.

Features

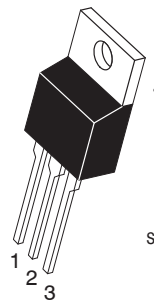
- High DC Current Gain –
 $h_{FE} = 2500$ (Typ) @ I_C
= 1.0 Adc
- Collector–Emitter Sustaining Voltage – @ 30 mAdc
 $V_{CEO(sus)} = 60$ Vdc (Min) – TIP110, TIP115
= 80 Vdc (Min) – TIP111, TIP116
= 100 Vdc (Min) – TIP112, TIP117
- Low Collector–Emitter Saturation Voltage –
 $V_{CE(sat)} = 2.5$ Vdc (Max) @ I_C
= 2.0 Adc
- Monolithic Construction with Built-in Base–Emitter Shunt Resistors
- Pb–Free Packages are Available*



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DARLINGTON 2 AMPERE COMPLEMENTARY SILICON POWER TRANSISTORS 60–80–100 VOLTS, 50 WATTS



TO-220AB
CASE 221A
STYLE 1

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

MARKING DIAGRAM



TIP11x = Device Code
x = 0, 1, 2, 5, 6, or 7
A = Assembly Location
Y = Year
WW = Work Week
G = Pb–Free Package

ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

TIP110, TIP111, TIP112 (NPN); TIP115, TIP116, TIP117 (PNP)

MAXIMUM RATINGS

Rating	Symbol	TIP110, TIP115	TIP111, TIP116	TIP112, TIP117	Unit
Collector–Emitter Voltage	V_{CEO}	60	80	100	Vdc
Collector–Base Voltage	V_{CB}	60	80	100	Vdc
Emitter–Base Voltage	V_{EB}	5.0			Vdc
Collector Current – Continuous – Peak	I_C	2.0 4.0			Adc
Base Current	I_B	50			mAdc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	50 0.4			W W/ $^\circ\text{C}$
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	2.0 0.016			W W/ $^\circ\text{C}$
Unclamped Inductive Load Energy – Figure 13	E	25			mJ
Operating and Storage Junction	T_J, T_{stg}	–65 to +150			$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction–to–Case	$R_{\theta JC}$	2.5	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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OFF CHARACTERISTICS

Collector–Emitter Sustaining Voltage (Note 1) ($I_C = 30 \text{ mAdc}, I_B = 0$)	TIP110, TIP115 TIP111, TIP116 TIP112, TIP117	$V_{CEO(sus)}$	60 80 100	– – –	Vdc
Collector Cutoff Current ($V_{CE} = 30 \text{ Vdc}, I_B = 0$) ($V_{CE} = 40 \text{ Vdc}, I_B = 0$) ($V_{CE} = 50 \text{ Vdc}, I_B = 0$)	TIP110, TIP115 TIP111, TIP116 TIP112, TIP117	I_{CEO}	– – –	2.0 2.0 2.0	mAdc
Collector Cutoff Current ($V_{CB} = 60 \text{ Vdc}, I_E = 0$) ($V_{CB} = 80 \text{ Vdc}, I_E = 0$) ($V_{CB} = 100 \text{ Vdc}, I_E = 0$)	TIP110, TIP115 TIP111, TIP116 TIP112, TIP117	I_{CBO}	– – –	1.0 1.0 1.0	mAdc
Emitter Cutoff Current ($V_{BE} = 5.0 \text{ Vdc}, I_C = 0$)		I_{EBO}	–	2.0	mAdc

ON CHARACTERISTICS (Note 1)

DC Current Gain ($I_C = 1.0 \text{ Adc}, V_{CE} = 4.0 \text{ Vdc}$) ($I_C = 2.0 \text{ Adc}, V_{CE} = 4.0 \text{ Vdc}$)		h_{FE}	1000 500	– –	–
Collector–Emitter Saturation Voltage ($I_C = 2.0 \text{ Adc}, I_B = 8.0 \text{ mAdc}$)		$V_{CE(sat)}$	–	2.5	Vdc
Base–Emitter On Voltage ($I_C = 2.0 \text{ Adc}, V_{CE} = 4.0 \text{ Vdc}$)		$V_{BE(on)}$	–	2.8	Vdc

DYNAMIC CHARACTERISTICS

Small–Signal Current Gain ($I_C = 0.75 \text{ Adc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ MHz}$)		h_{fe}	25	–	–
Output Capacitance ($V_{CB} = 10 \text{ Vdc}, I_E = 0, f = 0.1 \text{ MHz}$)	TIP115, TIP116, TIP117 TIP110, TIP111, TIP112	C_{ob}	– –	200 100	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$.

TIP110, TIP111, TIP112 (NPN); TIP115, TIP116, TIP117 (PNP)

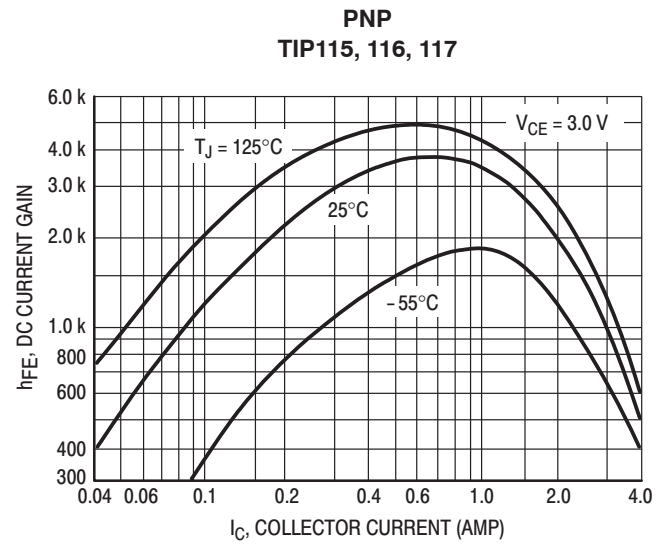
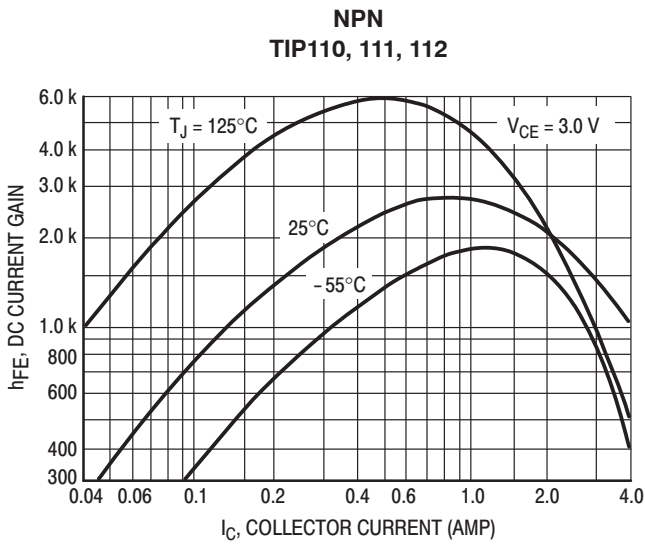


Figure 9. DC Current Gain

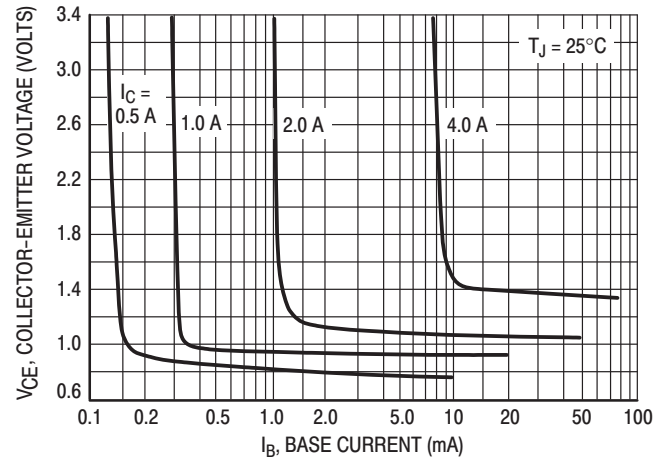
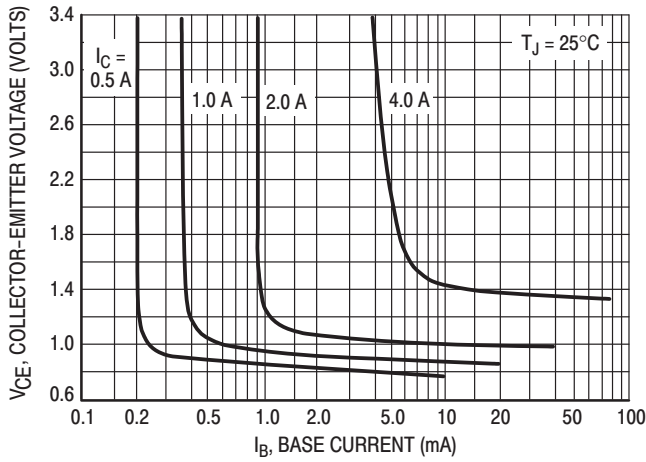


Figure 10. Collector Saturation Region

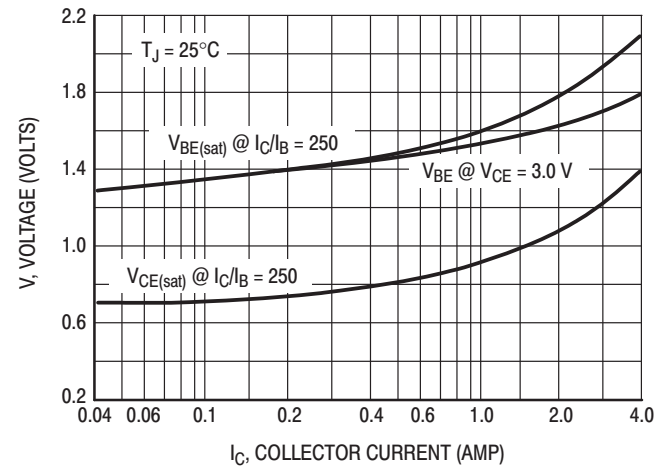
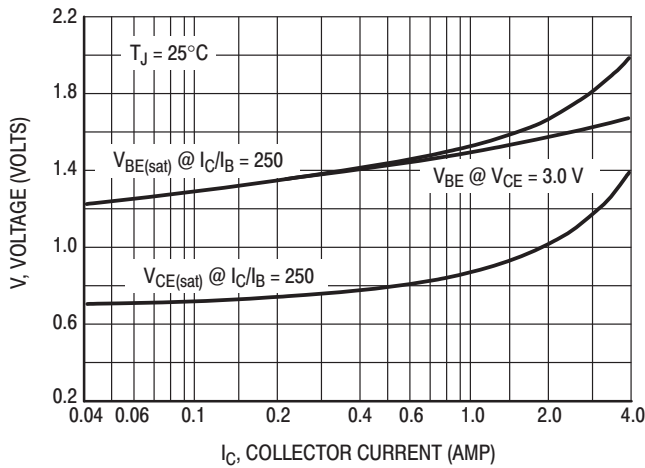


Figure 11. "On" Voltages

TIP100, TIP101, TIP102 (NPN); TIP105, TIP106, TIP107 (PNP)

Plastic Medium-Power Complementary Silicon Transistors

Designed for general-purpose amplifier and low-speed switching applications.

Features

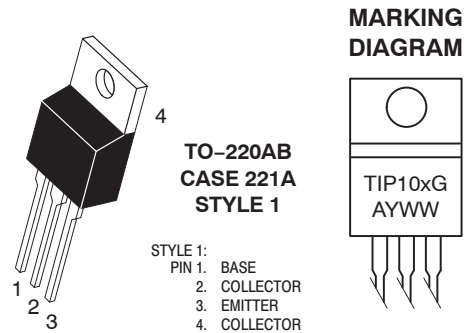
- High DC Current Gain –
 $h_{FE} = 2500$ (Typ) @ I_C
 $= 4.0$ Adc
- Collector–Emitter Sustaining Voltage – @ 30 mAdc
 $V_{CEO(sus)} = 60$ Vdc (Min) – TIP100, TIP105
 $= 80$ Vdc (Min) – TIP101, TIP106
 $= 100$ Vdc (Min) – TIP102, TIP107
- Low Collector–Emitter Saturation Voltage –
 $V_{CE(sat)} = 2.0$ Vdc (Max) @ I_C
 $= 3.0$ Adc
 $= 2.5$ Vdc (Max) @ $I_C = 8.0$ Adc
- Monolithic Construction with Built-in Base–Emitter Shunt Resistors
- Pb-Free Packages are Available*



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DARLINGTON 8 AMPERE COMPLEMENTARY SILICON POWER TRANSISTORS 60–80–100 VOLTS, 80 WATTS



TIP10x = Device Code
x = 0, 1, 2, 5, 6, or 7
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

TIP100, TIP101, TIP102 (NPN); TIP105, TIP106, TIP107 (PNP)

MAXIMUM RATINGS

Rating	Symbol	TIP100, TIP105	TIP101, TIP106	TIP102, TIP107	Unit
Collector – Emitter Voltage	V_{CEO}	60	80	100	Vdc
Collector – Base Voltage	V_{CB}	60	80	100	Vdc
Emitter – Base Voltage	V_{EB}	5.0			Vdc
Collector Current – Continuous – Peak	I_C	8.0 15			Adc
Base Current	I_B	1.0			Adc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	80 0.64			W W/ $^\circ\text{C}$
Unclamped Inductive Load Energy (1)	E	30			mJ
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	2.0 0.016			W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	–65 to +150			$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.56	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. $I_C = 1.1\text{ A}$, $L = 50\text{ mH}$, P.R.F. = 10 Hz, $V_{CC} = 20\text{ V}$, $R_{BE} = 100\ \Omega$

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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OFF CHARACTERISTICS

Collector–Emitter Sustaining Voltage (1) ($I_C = 30\text{ mAdc}$, $I_B = 0$)	TIP100, TIP105 TIP101, TIP106 TIP102, TIP107	$V_{CEO(sus)}$	60 80 100	– – –	Vdc
Collector Cutoff Current ($V_{CE} = 30\text{ Vdc}$, $I_B = 0$) ($V_{CE} = 40\text{ Vdc}$, $I_B = 0$) ($V_{CE} = 50\text{ Vdc}$, $I_B = 0$)	TIP100, TIP105 TIP101, TIP106 TIP102, TIP107	I_{CEO}	– – –	50 50 50	μAdc
Collector Cutoff Current ($V_{CB} = 60\text{ Vdc}$, $I_E = 0$) ($V_{CB} = 80\text{ Vdc}$, $I_E = 0$) ($V_{CB} = 100\text{ Vdc}$, $I_E = 0$)	TIP100, TIP105 TIP101, TIP106 TIP102, TIP107	I_{CBO}	– – –	50 50 50	μAdc
Emitter Cutoff Current ($V_{BE} = 5.0\text{ Vdc}$, $I_C = 0$)		I_{EBO}	–	8.0	mAdc

ON CHARACTERISTICS (1)

DC Current Gain ($I_C = 3.0\text{ Adc}$, $V_{CE} = 4.0\text{ Vdc}$) ($I_C = 8.0\text{ Adc}$, $V_{CE} = 4.0\text{ Vdc}$)		h_{FE}	1000 200	20,000 –	–
Collector–Emitter Saturation Voltage ($I_C = 3.0\text{ Adc}$, $I_B = 6.0\text{ mAdc}$) ($I_C = 8.0\text{ Adc}$, $I_B = 80\text{ mAdc}$)		$V_{CE(sat)}$	– –	2.0 2.5	Vdc
Base–Emitter On Voltage ($I_C = 8.0\text{ Adc}$, $V_{CE} = 4.0\text{ Vdc}$)		$V_{BE(on)}$	–	2.8	Vdc

DYNAMIC CHARACTERISTICS

Small–Signal Current Gain ($I_C = 3.0\text{ Adc}$, $V_{CE} = 4.0\text{ Vdc}$, $f = 1.0\text{ MHz}$)		h_{fe}	4.0	–	–
Output Capacitance ($V_{CB} = 10\text{ Vdc}$, $I_E = 0$, $f = 0.1\text{ MHz}$)	TIP105, TIP106, TIP107 TIP100, TIP101, TIP102	C_{ob}	– –	300 200	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$.

TIP100, TIP101, TIP102 (NPN); TIP105, TIP106, TIP107 (PNP)

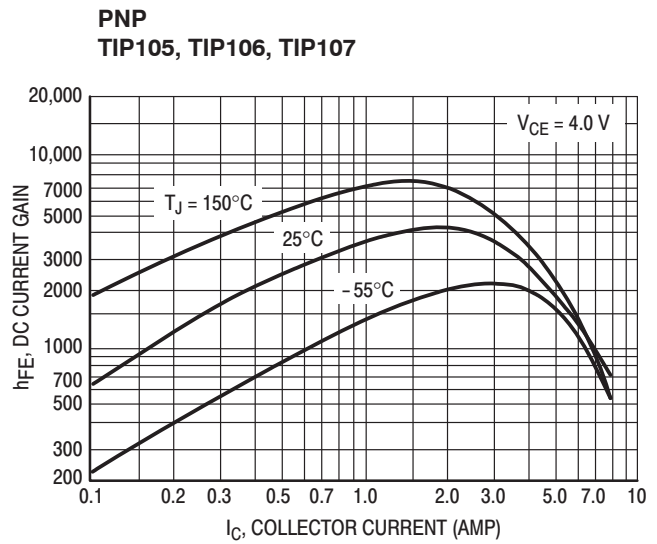
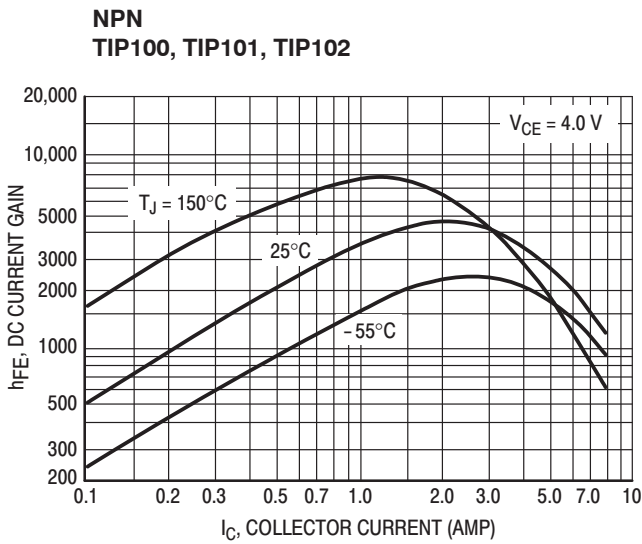


Figure 9. DC Current Gain

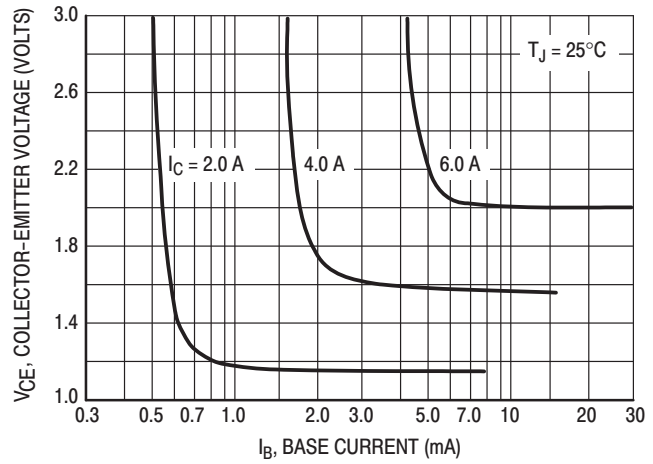
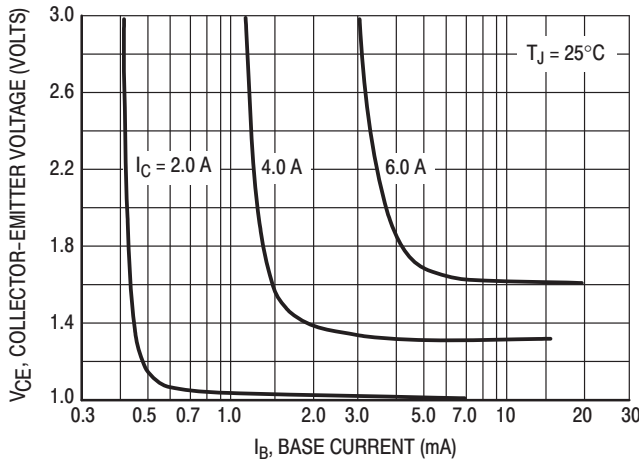


Figure 10. Collector Saturation Region

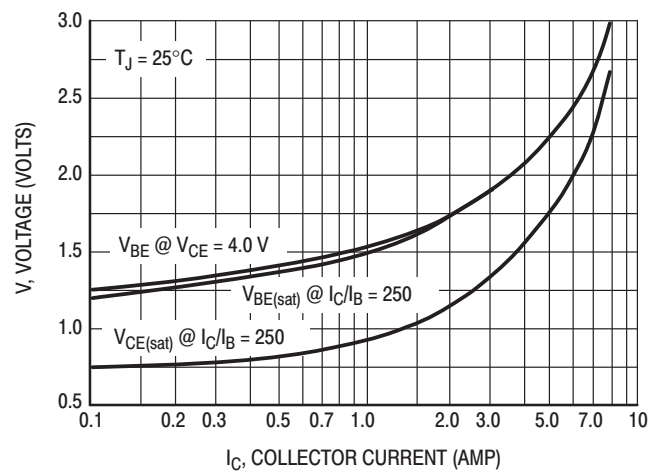
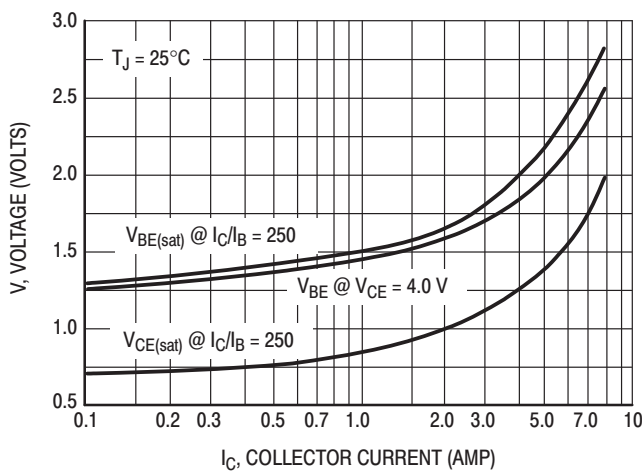
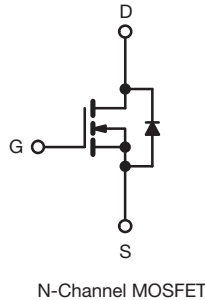
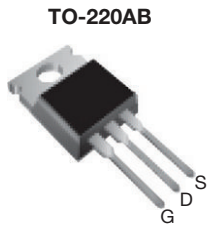


Figure 11. "On" Voltages

Power MOSFET

PRODUCT SUMMARY	
V_{DS} (V)	100
$R_{DS(on)}$ (Ω)	$V_{GS} = 10\text{ V}$ 0.54
Q_g max. (nC)	8.3
Q_{gs} (nC)	2.3
Q_{gd} (nC)	3.8
Configuration	Single



FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- 175 °C operating temperature
- Fast switching
- Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF510PbF
	SiHF510-E3
SnPb	IRF510
	SiHF510

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)					
PARAMETER	SYMBOL		LIMIT	UNIT	
Drain-Source Voltage	V_{DS}		100	V	
Gate-Source Voltage	V_{GS}		± 20		
Continuous Drain Current	V_{GS} at 10 V	$T_C = 25\text{ }^\circ\text{C}$	5.6	A	
		$T_C = 100\text{ }^\circ\text{C}$	4.0		
Pulsed Drain Current ^a	I_{DM}		20		
Linear Derating Factor			0.29	W/°C	
Single Pulse Avalanche Energy ^b	E_{AS}		75	mJ	
Repetitive Avalanche Current ^a	I_{AR}		5.6	A	
Repetitive Avalanche Energy ^a	E_{AR}		4.3	mJ	
Maximum Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$		P_D	43	W
Peak Diode Recovery dV/dt ^c			dV/dt	5.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{stg}		-55 to +175	°C	
Soldering Recommendations (Peak temperature) ^d	for 10 s		300		
Mounting Torque	6-32 or M3 screw		10	lbf · in	
			1.1	N · m	

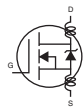

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 25\text{ V}$, starting $T_J = 25\text{ }^\circ\text{C}$, $L = 4.8\text{ mH}$, $R_g = 25\text{ }\Omega$, $I_{AS} = 5.6\text{ A}$ (see fig. 12).
- $I_{SD} \leq 5.6\text{ A}$, $dI/dt \leq 75\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 175\text{ }^\circ\text{C}$.
- 1.6 mm from case.



THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Case-to-Sink, Flat, Greased Surface	R_{thCS}	0.50	-	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.5	

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	100	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$	-	0.12	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0	-	4.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20\text{ V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}$	-	-	25	μA
		$V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$	-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$ $I_D = 3.4\text{ A}^b$	-	-	0.54	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 50\text{ V}, I_D = 3.4\text{ A}^b$	1.3	-	-	S
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V},$ $V_{DS} = 25\text{ V},$ $f = 1.0\text{ MHz},$ see fig. 5	-	180	-	pF
Output Capacitance	C_{oss}		-	81	-	
Reverse Transfer Capacitance	C_{rss}		-	15	-	
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}$ $I_D = 5.6\text{ A}, V_{DS} = 80\text{ V}$ $V_{DS} = 10\text{ V},$ see fig. 6 and fig. 13 ^b	-	-	8.3	nC
Gate-Source Charge	Q_{gs}		-	-	2.3	
Gate-Drain Charge	Q_{gd}		-	-	3.8	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 50\text{ V}, I_D = 5.6\text{ A}$ $R_g = 24\text{ }\Omega, R_D = 8.4\text{ }\Omega,$ see fig. 10 ^b	-	6.9	-	ns
Rise Time	t_r		-	16	-	
Turn-Off Delay Time	$t_{d(off)}$		-	15	-	
Fall Time	t_f		-	9.4	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 	-	4.5	-	nH
Internal Source Inductance	L_S		-	7.5	-	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	5.6	A
Pulsed Diode Forward Current ^a	I_{SM}		-	-	20	
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 5.6\text{ A}, V_{GS} = 0\text{ V}^b$	-	-	2.5	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = 5.6\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$	-	100	200	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	0.44	0.88	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\text{ }\%$.